



## 72|476

SQUARING SAW



With two parallelly arranged diamond precision cutting discs. Machine is suitable for squaring mono crystalline ingots with of work piece diameter of 150 - 230 mm (wafer format 125 x 125 mm or 156 x 156 mm). Segment lengths of 200 – 2500 mm can be processed. With water hydraulic guidance for thin diamond cutting discs as well as cutting force and automatic feed control.

- equipped for manual and fully automatic loading, for instance with help of an industrial robot
- high flexible machine concept
- flexible and easy processing of different ingot and segment lengths and diameters
- low investment costs
- high process stability
- high machine availability 97% acc. to SEMI E10
- low tool costs → high lifetime of cutting discs
- thin blade water hydraulic guidance for thin diamond cutting discs
- cutting force control for an optimized cutting process
- ingots as grown can be processed without preparation